

55avenue  
45/9  
12-17-01  
Docket: 0819-0524

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of

Nobuo AOI

Serial No. 09/809,043

Filed: March 16, 2001

For: INTERLAYER DIELECTRIC  
FILM, AND METHOD FOR  
FORMING THE SAME AND  
INTERCONNECTION

)

) Attention: Applications Branch

)

)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with  
The United States Postal Service with sufficient postage as First  
Class Mail in an envelope addressed to: Commissioner for Patents,  
Washington, D.C. 20231, on \_\_\_\_\_

**PRELIMINARY AMENDMENT**

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

Please preliminary amend the subject application as follows:

In the Specification:

Please amend the specification as follows:

Page 19, Line 11

*Q1* FIG. 2B is a view illustrating a structure of a second cross-linking molecule used in  
Example [2] 1 of the method for forming an interlayer dielectric film of the first embodiment.

Page 20 continuing on page 21 , line 24

*Q2* FIGS. [13A] 12A through [13C] 12C are views illustrating steps of a method for forming  
an interconnection of the third embodiment.

Page 21, line 2

*Q3* FIGS. [14A] 13A and [14B] 13B are views illustrating steps of the method for forming an  
interconnection of the third embodiment.